Analog Input Output Module

Project Title: Designed for: Public Release

Assembly Variant: 001

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Not in version control

SVN Rev:

TIDA-00310

Number:

Rev:

E2

PCB Number: TIDA-00310

PCB Rev: E2

PCB

LOGO

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Label Assembly Note

ZZ1

Text Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Text Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Text Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Text Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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